



US 20220377896A1

(19) **United States**(12) **Patent Application Publication**
SALKOVIC et al.(10) **Pub. No.: US 2022/0377896 A1**(43) **Pub. Date: Nov. 24, 2022**(54) **COMPONENT CARRIER WITH A
MAGNETIC ELEMENT AND A
MANUFACTURING METHOD****Publication Classification**

(51) **Int. Cl.**
H05K 1/16 (2006.01)
H01F 17/00 (2006.01)
H05K 1/09 (2006.01)
H05K 3/12 (2006.01)

(52) **U.S. Cl.**
CPC *H05K 1/165* (2013.01); *H01F 17/0006*
(2013.01); *H05K 1/09* (2013.01); *H05K*
3/1216 (2013.01); *H05K 2201/0358* (2013.01);
H05K 2201/0376 (2013.01); *H05K 2203/308*
(2013.01)

(71) Applicant: **AT &S Austria Technologie &
Systemtechnik Aktiengesellschaft,**
Leoben (AT)(72) Inventors: **Ivan SALKOVIC**, Zagreb (HR);
Vanessa LÓPEZ BLANCO, Vimianzo
(ES)(21) Appl. No.: **17/663,418**(22) Filed: **May 13, 2022**(30) **Foreign Application Priority Data**

May 18, 2021 (EP) 21174488.3

(57) **ABSTRACT**

A component carrier includes a stack including at least one electrically conductive layer structure and/or at least one electrically insulating layer structure, a magnetic element assembled to the stack, and a dielectric layer structure on the stack. The magnetic element includes an embedded inductive element. The dielectric layer structure at least partially surrounds the magnetic element. Further, a manufacturing method and a use of photo-imaging are described.

